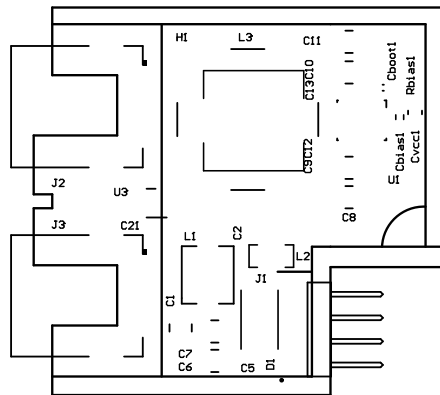


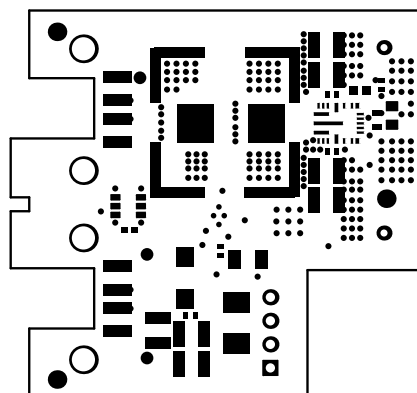
For evaluation only; not FCC approved for resale.

LBL1

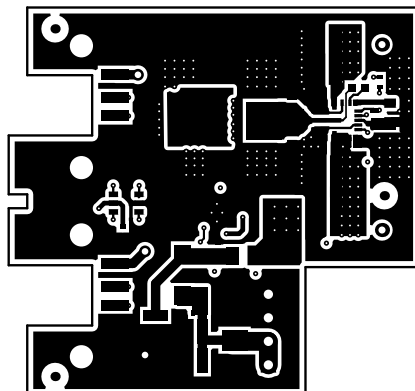
TIDA-01388E1- [REDACTED] (P)



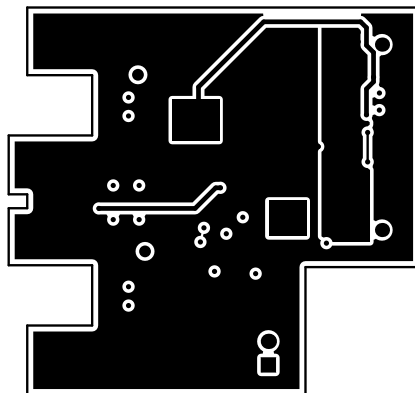
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01388	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-01388		
PLOT NAME = Top Overlay	GENERATED : 9/22/2017 7:50:11 PM	TEXAS INSTRUMENTS	



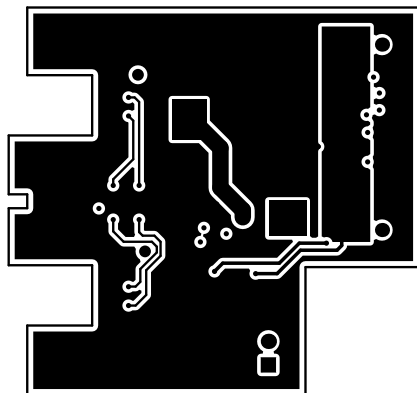
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01388	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01388		
PLOT NAME = Top Solder Mask	GENERATED : 9/22/2017 7:50:12 PM	TEXAS INSTRUMENTS	



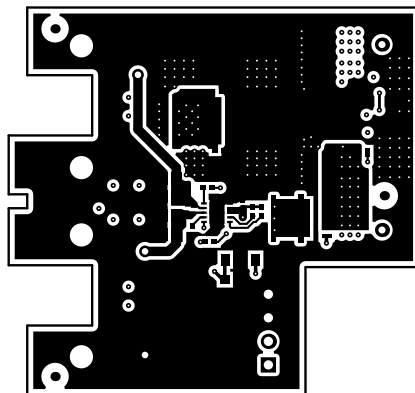
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01388	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-01388		
PLOT NAME = Top Layer	GENERATED : 9/22/2017 7:50:13 PM	TEXAS INSTRUMENTS	



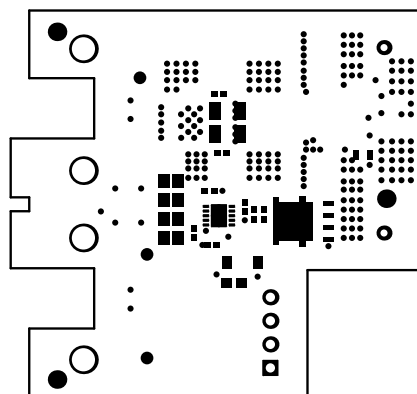
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01388	REV: E1	SVN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01388		
PLOT NAME = Signal 1	GENERATED : 9/22/2017 7:50:14 PM	TEXAS INSTRUMENTS	



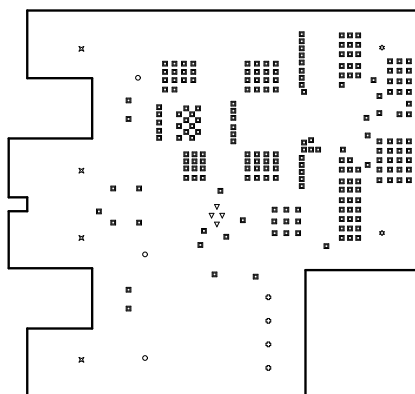
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01388	REV: E1	SVN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01388		
PLOT NAME = Signal 2	GENERATED : 9/22/2017 7:50:15 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01388	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-01388		
PLOT NAME = Bottom Layer	GENERATED : 9/22/2017 7:50:16 PM	TEXAS INSTRUMENTS	

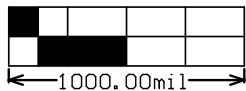
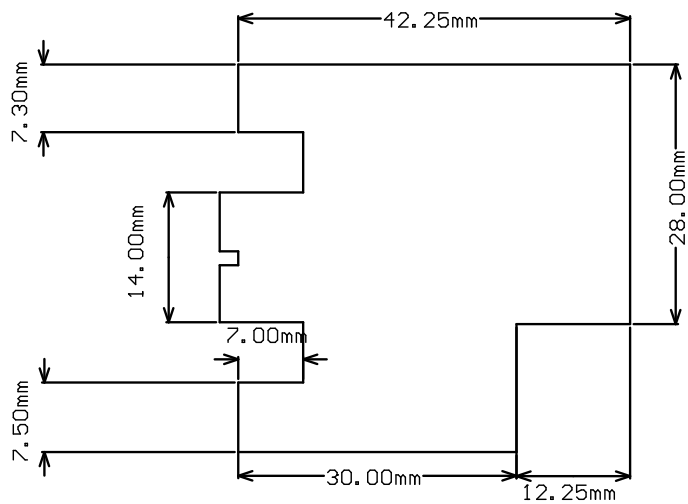


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01388	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01388		
PLOT NAME = Bottom Solder Mask	GENERATED : 9/22/2017 7:50:17 PM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
▽	4	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
■	210	8.00mil (0.203mm)	PTH	Round	Top Layer - Bottom Layer	
○	3	28.00mil (0.711mm)	PTH	Round	Top Layer - Bottom Layer	
☆	2	30.00mil (0.762mm)	PTH	Round	Top Layer - Bottom Layer	
⊕	4	39.37mil (1.000mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	4	98.43mil (2.500mm)	PTH	Round	Top Layer - Bottom Layer	
	227 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01388	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01388		
PLOT NAME = Drill Drawing	GENERATED : 9/22/2017 7:50:19 PM	TEXAS INSTRUMENTS	



1000.00mil

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01388	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-01388		
PLOT NAME = Board Dimensions	GENERATED : 9/22/2017 7:50:20 PM	TEXAS INSTRUMENTS	

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